

Title (en)
SEPARATION MODULE AND METHOD FOR PRODUCING THE SAME

Title (de)
SEPARATIONSMODUL UND VERFAHREN ZU SEINER HERSTELLUNG

Title (fr)
MODULE DE SEPARATION ET SON PROCEDE DE PRODUCTION

Publication
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Application
EP 01957806 A 20010519

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Abstract (en)
[origin: WO0187469A1] The aim of the invention is to provide a separation module that does not have the disadvantages of metal, glass or plastic housings and that at the same time allows to produce a separation layer that is as flawless as possible. To this end, the inventive separation module comprising a housing and a separation element retained thereby. The invention is further characterized in that a) the separation module is composed of a housing produced from a dense ceramic material and of separation element supports produced from a porous ceramic material; b) the separation element supports are coated with a separation layer either on the feed side or on the permeate side thereof; and c) the separation layer is applied on the separation element supports after the fully ceramic separation module has been assembled. The inventive product is especially but not exclusively useful in chemical process engineering in the broader sense thereof.

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